

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT7563576

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	SATOSHI TAKASHIMA	09/16/2022
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	SONY GROUP CORPORATION	
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<b>State/Country:</b>	JAPAN	
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<b>PROPERTY NUMBERS Total: 1</b>		
<b>Property Type</b>	<b>Number</b>	
<b>Application Number:</b>	17910382	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(571)376-6334	
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<b>ATTORNEY DOCKET NUMBER:</b>	18867US01	
<b>NAME OF SUBMITTER:</b>	CHI PARK	
<b>SIGNATURE:</b>	/Chi Park/	
<b>DATE SIGNED:</b>	09/28/2022	
<b>Total Attachments: 1</b>		



**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN  
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

<b>Title of Invention</b>	<b>SIGNAL PROCESSING DEVICE, SIGNAL PROCESSING METHOD, AND PARAMETER SEARCH METHOD</b>
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As the below named inventor, I hereby declare that:

This declaration is directed to: ☐ The attached application, or

☒ United States application or PCT international application number PCT/JP2021/005069  
filed on 10 February 2021.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

WHEREAS, Sony Group Corporation, Sony Semiconductor Solutions Corporation, with offices at  
1-7-1 KONAN, MINATO-KU, TOKYO, JAPAN ; 4-14-1 Asahicho, Atsugi-shi, Kanagawa, Japan,  
respectively (hereinafter referred to as ASSIGNEE(S)), and desirous of acquiring all interest in, to and under said invention,  
said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor  
in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and  
sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE(S),  
their successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions  
and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted  
for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the  
Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other  
international agreements to which the United States adheres, and to any other benefits accruing or to accrue to me with respect to the filing of  
applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the  
Commissioner of Patents to issue said Letters Patent to said ASSIGNEE(S), as assignee(s) of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of  
said ASSIGNEE(S) or their designee(s), as ASSIGNEE(S) or their successors, assigns, and legal representatives may from time-to-  
time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in  
said invention, applications, and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application  
for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent  
which may be granted for my aforesaid invention, as said ASSIGNEE(S) thereof shall hereafter require and prepare at their own expense;

And I further agree that ASSIGNEE(S) will, upon their request, be provided promptly with all pertinent facts and documents relating to  
said application, said invention, and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me  
and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict  
with this assignment and sale.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment  
of not more than five (5) years or both.

LEGAL NAME OF INVENTOR

Inventor: SATOSHI TAKASHIMA Date: 16 / 09 / 2022

Signature: /Satoshi Takashima/